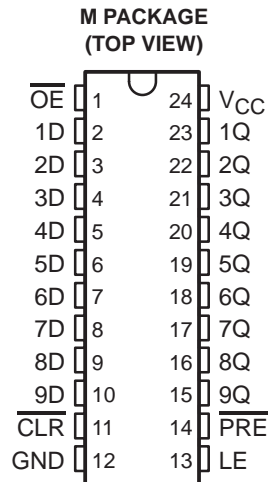


# CD74FCT843A BiCMOS 9-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS

SCBS727 – JULY 2000

- BiCMOS Technology With Low Quiescent Power
- Buffered Inputs
- Noninverted Outputs
- Input/Output Isolation From  $V_{CC}$
- Controlled Output Edge Rates
- 48-mA Output Sink Current
- Output Voltage Swing Limited to 3.7 V
- SCR Latch-Up-Resistant BiCMOS Process and Circuit Design
- Packaged in Plastic Small-Outline Package



## description

The CD74FCT843A is a 9-bit, bus-interface, D-type latch with 3-state outputs, designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The device uses a small-geometry BiCMOS technology. The output stage is a combination of bipolar and CMOS transistors that limits the output high level to two diode drops below  $V_{CC}$ . This resultant lowering of output swing (0 V to 3.7 V) reduces power-bus ringing [a source of electromagnetic interference (EMI)] and minimizes  $V_{CC}$  bounce and ground bounce and their effects during simultaneous output switching. The output configuration also enhances switching speed and is capable of sinking 48 mA.

The CD74FCT843A outputs are transparent to the inputs when the latch-enable (LE) input is high. The latches are transparent D-type latches. When LE goes low, the data is latched. The output-enable ( $\overline{OE}$ ) input controls the 3-state outputs. When  $\overline{OE}$  is high, the outputs are in the high-impedance state. The latch operation is independent of the state of the output enable. This device, having preset ( $\overline{PRE}$ ) and clear ( $\overline{CLR}$ ), are ideal for parity-bus interfacing. When  $\overline{PRE}$  is low, the outputs are high if  $\overline{OE}$  is low.  $\overline{PRE}$  overrides  $\overline{CLR}$ . When  $\overline{CLR}$  is low, the outputs are low if  $\overline{OE}$  is low. When  $\overline{CLR}$  is high, data can be entered into the latch. The device provides noninverted outputs.

$\overline{OE}$  does not affect the internal operations of the latch. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

The CD74FCT843A is characterized for operation from 0°C to 70°C.

FUNCTION TABLE  
(each latch)

INPUTS					OUTPUT
$\overline{PRE}$	$\overline{CLR}$	$\overline{OE}$	LE	D	Q
L	X	L	X	X	H
H	L	L	X	X	L
H	H	L	H	L	L
H	H	L	H	H	H
H	H	L	L	X	$Q_0$
X	X	H	X	X	Z



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

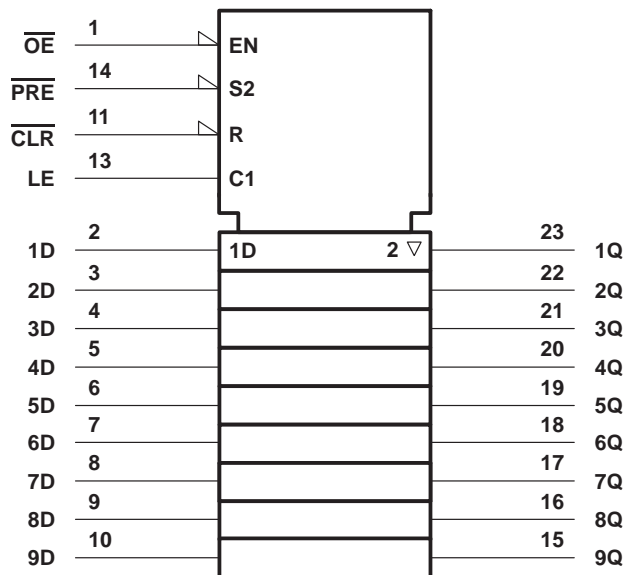
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# CD74FCT843A BiCMOS 9-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS

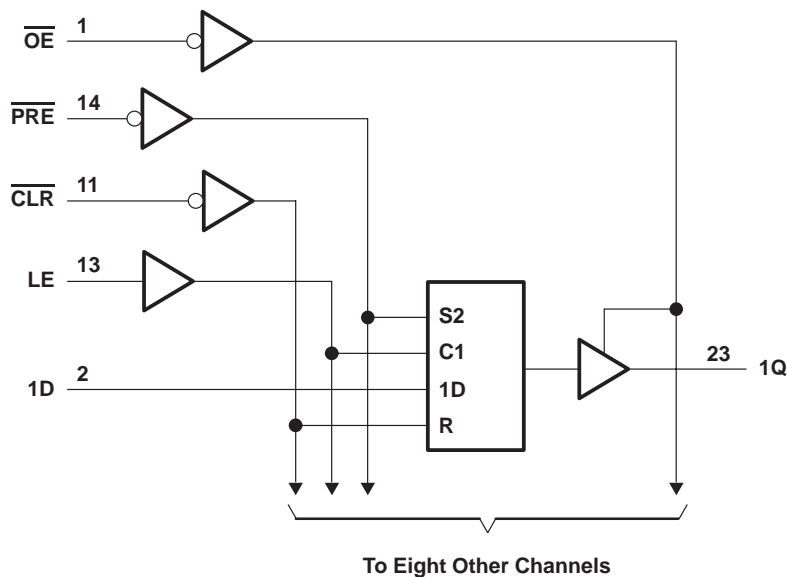
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## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)



# CD74FCT843A

## BiCMOS 9-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

DC supply voltage range, $V_{CC}$	–0.5 V to 6 V
DC input clamp current, $I_{IK}$ ( $V_I < -0.5$ V)	–20 mA
DC output clamp current, $I_{OK}$ ( $V_O < -0.5$ V)	–50 mA
DC output sink current per output pin, $I_{OL}$	70 mA
DC output source current per output pin, $I_{OH}$	–30 mA
Continuous current through $V_{CC}$ , ( $I_{CC}$ )	237 mA
Continuous current through GND	453 mA
Package thermal impedance, $\theta_{JA}$ (see Note 1)	46°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

### recommended operating conditions (see Note 2)

	MIN	MAX	UNIT
$V_{CC}$ Supply voltage	4.75	5.25	V
$V_{IH}$ High-level input voltage	2		V
$V_{IL}$ Low-level input voltage		0.8	V
$V_I$ Input voltage	0	$V_{CC}$	V
$V_O$ Output voltage	0	$V_{CC}$	V
$I_{OH}$ High-level output current		–15	mA
$I_{OL}$ Low-level output current		48	mA
$\Delta t/\Delta v$ Input transition rise or fall rate	0	10	ns/V
$T_A$ Operating free-air temperature	0	70	°C

NOTE 2: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### electrical characteristics over recommended operating temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CC}$	$T_A = 25^\circ\text{C}$		MIN	MAX	UNIT
			MIN	MAX			
$V_{IK}$	$I_I = -18$ mA	4.75 V		–1.2		–1.2	V
$V_{OH}$	$I_{OH} = -15$ mA	4.75 V	2.4		2.4		V
$V_{OL}$	$I_{OL} = 48$ mA	4.75 V		0.55		0.55	V
$I_I$	$V_I = V_{CC}$ or GND	5.25 V		$\pm 0.1$		$\pm 1$	$\mu\text{A}$
$I_{OZ}$	$V_O = V_{CC}$ or GND	5.25 V		$\pm 0.5$		$\pm 10$	$\mu\text{A}$
$I_{OS}^\ddagger$	$V_I = V_{CC}$ or GND, $V_O = 0$	5.25 V		–75		–75	mA
$I_{CC}$	$V_I = V_{CC}$ or GND, $I_O = 0$	5.25 V		8		80	$\mu\text{A}$
$\Delta I_{CC}^\S$	One input at 3.4 V, Other inputs at $V_{CC}$ or GND	5.25 V		1.6		1.6	mA
$C_i$	$V_I = V_{CC}$ or GND			10		10	pF
$C_o$	$V_O = V_{CC}$ or GND			15		15	pF

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed 100 ms.

§ This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or  $V_{CC}$ .



**CD74FCT843A**  
**BiCMOS 9-BIT BUS-INTERFACE D-TYPE LATCH**  
**WITH 3-STATE OUTPUTS**

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timing requirements over recommended operating temperature conditions (unless otherwise noted) (see Figure 1)

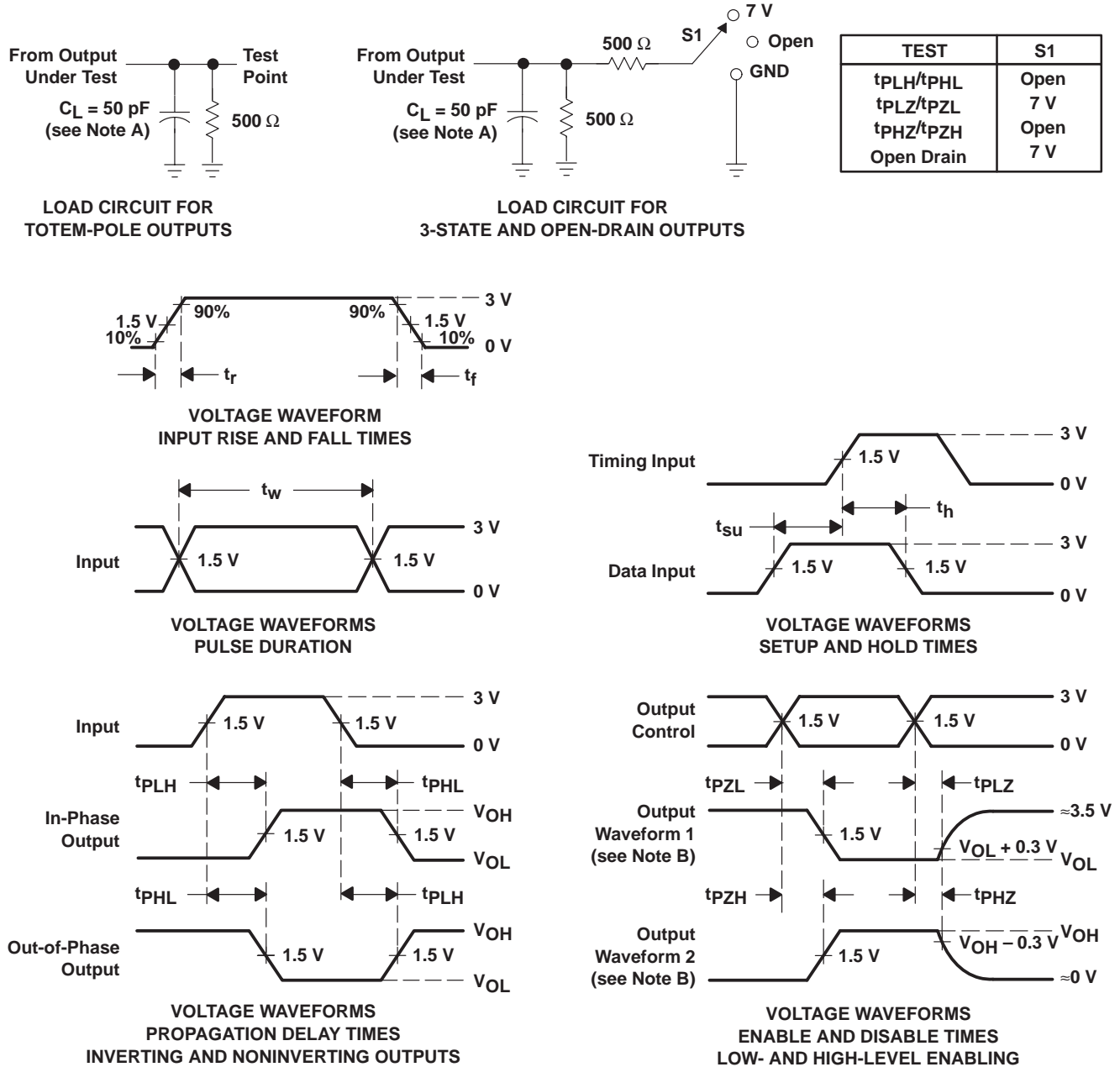
		MIN	MAX	UNIT
$t_w$	Pulse duration	CLR low	8	ns
		$\overline{\text{PRE}}$ low	8	
		LE low	4	
$t_{su}$	Setup time	Data before LE↓	2.5	ns
		$\overline{\text{PRE}}$ inactive	1.4	
		$\overline{\text{CLR}}$ inactive	1.4	
$t_h$	Hold time	Data before LE↓	2.5	ns
$t_{rec}$	Recovery time	$\overline{\text{PRE}}, \overline{\text{CLR}}$	14	ns

switching characteristics over recommended operating temperature conditions (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$	MIN	MAX	UNIT
			TYP			
$t_{pd}$	D	Q	6.8	1.5	9	ns
	LE		9	1.5	12	
$t_{PLH}$	$\overline{\text{PRE}}$	Q	9	1.5	12	ns
$t_{PHL}$	$\overline{\text{CLR}}$	Q	9.8	1.5	13	ns
$t_{en}$	$\overline{\text{OE}}$	Q	10.5	1.5	14	ns
$t_{dis}$	$\overline{\text{OE}}$	Q	6	1.5	8	ns



PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r$  and  $t_f = 2.5 \text{ ns}$ .  
 D. The outputs are measured one at a time with one input transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD74FCT843AM	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74FCT843AME4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74FCT843AMG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

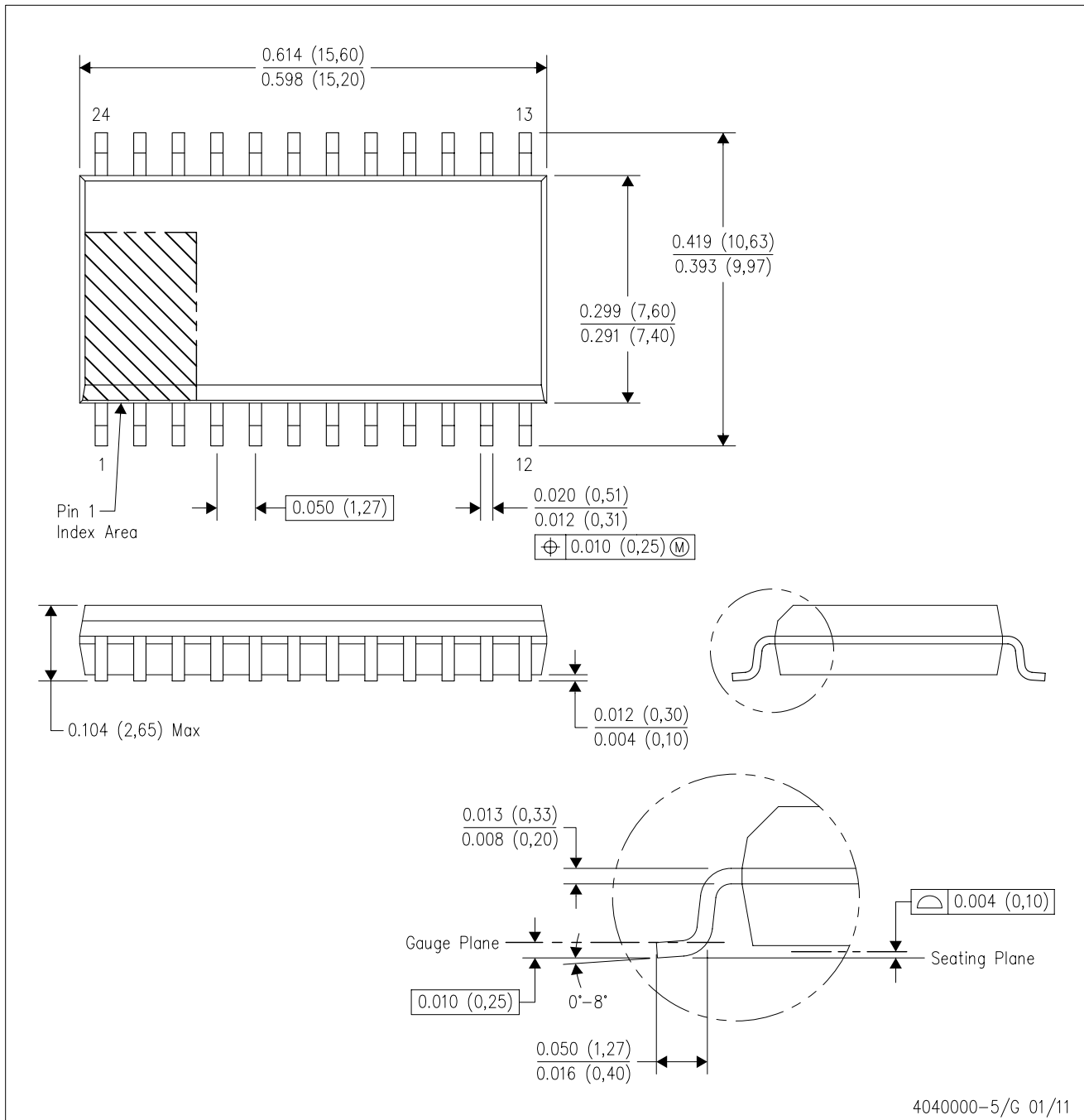
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DW (R-PDSO-G24)

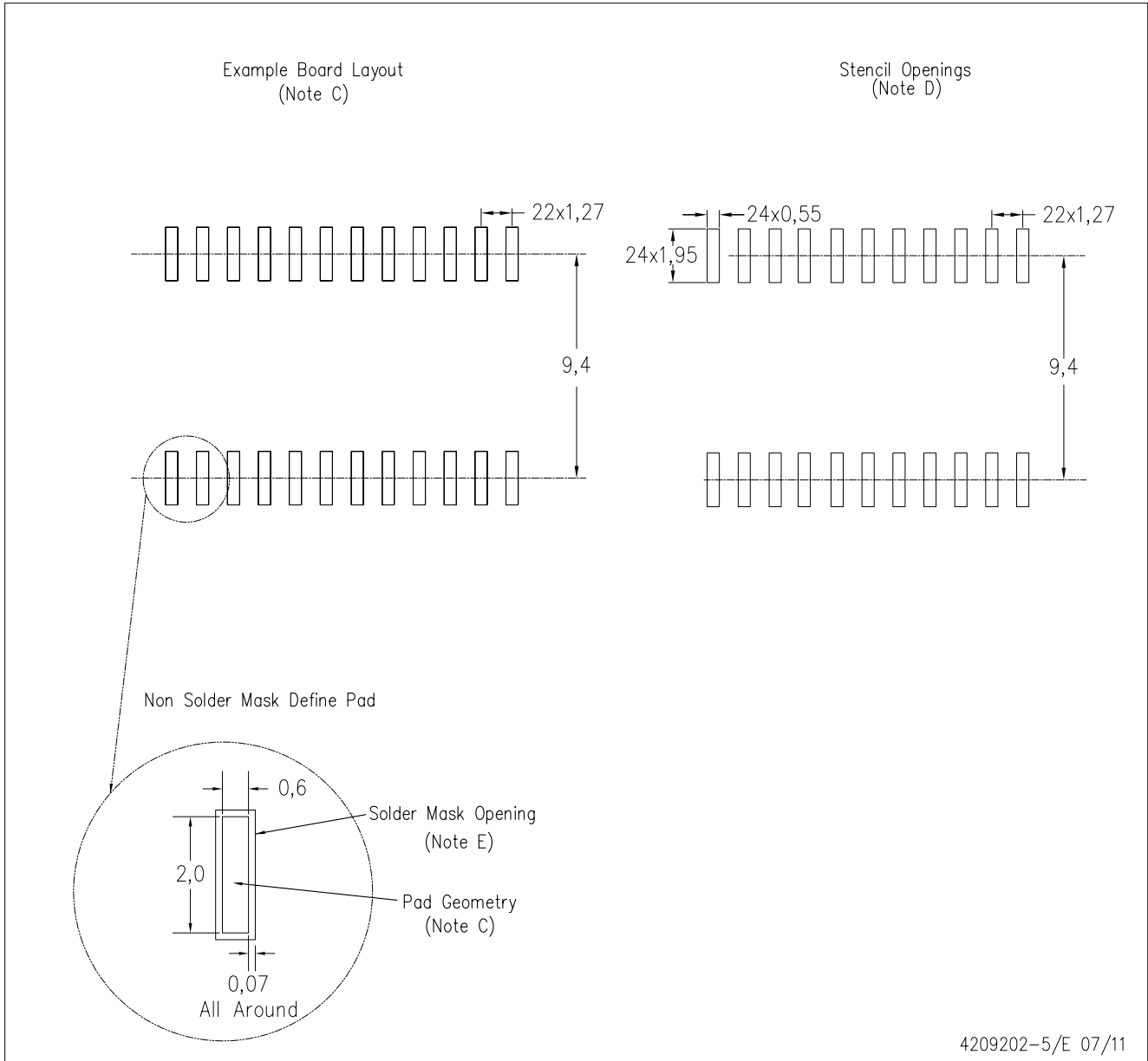
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AD.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



4209202-5/E 07/11

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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